



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-06-09
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HZGR*LM08AB6	A	SH1A	2014-06-09
Amount	UoM	Unit type	ST ECOPACK Grade	
290.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	6.085X6.614X2.3	4	gull wing	
Comment	Package: TO-252 DPAK Cu Wire			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HZGR*LM08AB6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	1.271	mg	supplier	die	Silicon (Si)	7440-21-3		1.23	mg	967742	4241
				supplier	metallization	Aluminium (Al)	7429-90-5		0.016	mg	12589	55
				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.005	mg	3934	17
				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.007	mg	5507	24
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.001	mg	787	3
				supplier	back side metallization	Gold (Au)	7440-57-5		0.003	mg	2360	10
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.009	mg	7081	31
Leadframe	Copper & its alloys	180.356	mg	supplier	alloy	Copper (Cu)	7440-50-8		180.122	mg	998703	621110
				supplier	alloy	Iron (Fe)	7439-89-6		0.083	mg	460	286
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.151	mg	837	521
Soft solder	Other organic materials	1.362	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	1.301	mg	955213	4486
				supplier	solder	Silver (Ag)	7440-22-4		0.034	mg	24963	117
				supplier	solder	Tin (Sn)	7440-31-5		0.027	mg	19824	93
Bonding wire	Other inorganic materials	0.103	mg	supplier	wire	Copper (Cu)	7440-50-8		0.103	mg	1000000	355
				supplier	mold compound	Epoxy Resin	Proprietary		3.176	mg	30001	10952
				supplier	mold compound	2,2'-((3,3',5,5'-tetramethyl-(1,1'-biphenyl)-4,4'	EC 413-900-7		4.235	mg	40005	14603
				supplier	mold compound	phenol resin	Proprietary		5.293	mg	49999	18252
encapsulation	Other organic materials	105.863	mg	supplier	mold compound	Silica, vitreous	60676-86-0		92.63	mg	874999	319414
				supplier	mold compound	Carbon black	1333-86-4		0.529	mg	4997	1824
				supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3603
connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3603